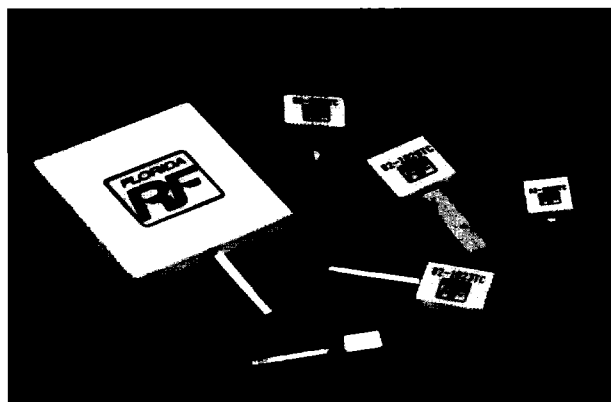


POWER PAK HIGH FREQUENCY/POWER CHIP TERMINATIONS



The POWER PAK Version of our chip terminations offer the same rugged construction as our flange mounted devices, while affording a much smaller package size. The terminations are supplied with alumina ceramic lids and tin plated tab contacts of sufficient length to allow for lead forming and easy mounting to the circuit.

TERMINATIONS

General Specifications

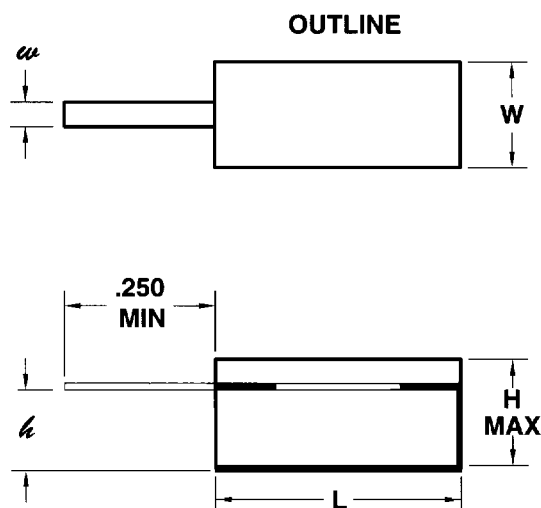
- Resistance 50 Ohms $\pm$ 2% standard

OTHER RESISTANCE VALUES AND TOLERANCES AVAILABLE UPON REQUEST.

Material Specifications

- Solderable Ground Plane Fired Platinum Silver
- Substrate Beryllium Oxide Ceramic
- Resistive Element Proprietary Nichrome Thin Film
- Tab Contact Beryllium Copper, Tin plated per MIL-T-10727
- Environment Meets applicable portions of MIL-E-5400 and MIL-R-55342

POWER WATTS	PART NUMBER	W	L	H max	ϵ	μ	Frequency VSWR
10	82-1033TC	0.100	0.200	0.080	0.040	0.040	DC - 10.0 GHZ 1.30:1
10	82-1045TC	0.200	0.100	0.090	0.040	0.040	DC - 18.0 GHZ 1.35:1
30	82-1005TC	0.250	0.250	0.085	0.040	0.060	DC - 4.0 GHZ 1.20:1
40	82-1039TC	0.250	0.250	0.085	0.040	0.060	DC - 6.0 GHZ 1.20:1
40	82-1030TC	0.350	0.230	0.085	0.040	0.040	DC - 6.0 GHZ 1.30:1
60	82-1032TC	0.375	0.250	0.085	0.040	0.060	DC - 6.0 GHZ 1.20:1
100	82-1038TC	0.350	0.230	0.085	0.040	0.040	DC - 6.0 GHZ 1.30:1
120	82-1031TC	0.350	0.230	0.085	0.040	0.040	DC - 2.0 GHZ 1.10:1
150	82-1023TC	0.250	0.375	0.085	0.040	0.040	DC - 4.0 GHZ 1.35:1
250	82-1029TC	0.375	0.375	0.085	0.040	0.120	DC - 2.0 GHZ 1.15:1
400	82-1017TC	1.000	1.000	0.110	0.060	0.060	DC - 1.0 GHZ 1.20:1
500	82-1040TC	0.500	0.500	0.080	0.040	0.060	DC - 1.5 GHZ 1.35:1



Notes

Power ratings are average power and based on maximum film temperature of 150°C, and heat sink temperature of 100°C maximum.

Ordering Information

Example 82 - 1XXXTC

Chip Termination _____
Platinum Silver Ground Plane _____
Tab & Cover _____